RELIABILITY REPORT

FOR

MAX4730EXT+

PLASTIC ENCAPSULATED DEVICES

July 27, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX4730EXT+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX4729/MAX4730 single-pole/double-throw (SPDT) switches operate from a single supply ranging from +1.8V to +5.5V. These switches provide low 3.5 on-resistance (RON), as well as 0.45 RON flatness with a +2.7V supply. These devices typically consume only 1nA of supply current, making them ideal for use in lowpower, portable applications. The MAX4729/MAX4730 feature low-leakage currents over the extended temperature range, TTL/CMOS-compatible digital logic, and excellent AC characteristics. The MAX4729/MAX4730 are available in small 6-pin SC70 and 6-pin µDFN packages. The MAX4729/MAX4730 are offered in three pinout configurations to ease design. The MAX4729/MAX4730 are specified over the extended -40°C to +85°C temperature range.

II. Manufacturing Information

A. Description/Function:	Low-Voltage 3.5 Ohm, SPDT, CMOS Analog Switches
B. Process:	E35
C. Number of Device Transistors:	
D. Fabrication Location:	Texas
E. Assembly Location:	Malaysia, Thailand
F. Date of Initial Production:	April 24, 2004

III. Packaging Information

A. Package Type:	6-pin SC70
B. Lead Frame:	
C. Lead Finish:	100% matte Tin
D. Die Attach:	Non-conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-0836
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	326°C/W
K. Single Layer Theta Jc:	115°C/W

IV. Die Information

A. Dimensions:	28 X 31 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.35µm
F. Minimum Metal Spacing:	0.35µm
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 125°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 126 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 8.5 \times 10^{-9}$

$\lambda = 8.5$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the E35 Process results in a FIT Rate of 0.28 @ 25C and 4.84 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The AS19-5 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX4730EXT+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 125°C Biased Time = 192 hrs.	DC Parameters & functionality	126	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data